L Number	Hits	Search Text	DB	Time stamp
5	3	(("6344401") or ("6165885") or	USPAT	2004/01/12 07:56
ŀ		("5834320")).PN.		
6	244	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:03
İ		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
İ		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
<u>.</u>		@ad<=20000616	IBM_TDB	0004/01/10 00 0:
7	244	(wafer and (metal adj (film or layer)) and	USPAT;	2004/01/12 08:04
1		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB; EPO; JPO;	
İ		adj arrays) or (BGA)) and semiconductor and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
ŀ		@ad<=20000616	IBM TDB	
8	166		USPĀT;	2004/01/12 08:05
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
İ		grid adj arrays) or (BGA)) and	EPO; JPO;	
İ	:	semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
İ		separat\$5)) and @ad<=20000616) and	IBM_TDB	
_		align\$6		
9	688	(438/455).CCLS.	USPAT;	2004/01/12 08:08
·			US-PGPUB:	[
i			EPO; JPO;	
i			DERWENT; IBM TDB	
12	1 2	438/455,456,457,458,459,460,461,462,464.ccl		2004/01/12 08:11
1	12	and (wafer and (metal adj (film or layer))	US-PGPUB;	2004/01/12 00:11
ļ		and (attach\$5 or bond\$4) and ((balls adj	EPO; JPO;	
į	•	grid adj arrays) or ("BGA")) and (dic\$4 or	DERWENT;	
ŀ		cut\$4 or separat\$5)) and @ad<=20000616	IBM_TDB	
11	97	438/\$.ccls. and (wafer and (metal adj	USPAT;	2004/01/12 08:52
į		(film or layer)) and (attach\$5 or bond\$4)	US-PGPUB;	
İ		and ((balls adj grid adj arrays) or	EPO; JPO;	
į		("BGA")) and (dic\$4 or cut\$4 or	DERWENT;	
	240	separat\$5)) and @ad<=20000616	IBM_TDB	2004/01/12 22 22
	348		USPAT	2004/01/12 08:08
_	258 94	, · · · · · · · · · · · · · · · · · · ·	USPAT USPAT	2002/07/03 08:58 2002/07/03 08:58
_	59		USPAT	2002/07/03 08:58
_	681		USPAT	2002/07/03 00:30
-	401	438/15,110,113,114.ccls. and test\$3	USPAT	2001/08/07 15:09
-	272	(438/15,110,113,114.ccls. and test\$3) and	USPAT	2001/08/07 15:10
İ		(dice\$4 or cut\$5)		
-	901	438/15,110,113,114.ccls.	USPAT;	2002/02/04 09:53
İ			EPO; JPO;	
i	4.60	/39/15 110 112 114 agla and backs	DERWENT	2002/02/04 00:54
_	460	438/15,110,113,114.ccls. and test\$3	USPAT; EPO; JPO;	2002/02/04 09:54
			DERWENT	
_	325	(438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:26
İ		(dic\$5 or cut\$5)	EPO; JPO;	
İ			DERWENT	
-	5	_ , , , , , , , , , , , , , , , , , , ,	USPAT	2003/10/24 12:32
		or ("6309909") or ("6326697")).PN.		
-	7	, , , , , , , , , , , , , , , , , , , ,	USPAT	2002/02/05 09:49
İ		or ("6309909") or ("6326697") or		
•	226	("5858815") or ("5137836")).PN.	110 D 2 M	2002/02/25 22 22
_	326		USPAT;	2002/02/05 08:28
		(dic\$5 or cut\$5)	EPO; JPO; DERWENT	
_	o	((438/15,110,113,114.ccls. and test\$3) and	USPAT;	2002/02/05 08:33
ļ		(dic\$5 or cut\$5)) and (magnet\$7 adj	EPO; JPO;	2002/02/03 00:33
		align\$5)	DERWENT	
_	170		USPAT;	2002/02/05 08:32
ļ	= · •	(dic\$5 or cut\$5)) and (align\$5)	EPO; JPO;	= ,
			DERWENT	
-	2705	magnet\$7 adj align\$5	USPAT;	2002/02/05 08:56
			EPO; JPO;	
ļ	_		DERWENT	0000/00/55
-	0	(magnet\$7 adj align\$5) and (wafer adj20	USPAT;	2002/02/05 08:37
		dielectric adj tape)	EPO; JPO;	
			DERWENT	

-	0	wafer adj20 dielectric adj tape	USPAT;	2002/02/05 08:37
1			EPO; JPO;	
			DERWENT	
-	0	wafer adj dielectric adj tape	USPAT;	2002/02/05 08:38
			EPO; JPO;	
			DERWENT	
-	248	(magnet\$7 adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
			EPO; JPO;	
			DERWENT	
-	0	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:49
		(charged adj slot)	EPO; JPO;	
			DERWENT	
_	0	(magnet\$7 adj align\$5) and (charged adj	USPAT;	2002/02/05 08:49
		slot)	EPO; JPO;	
			DERWENT	
_	613	(magnet\$7 adj align\$5) and ring	USPAT;	2002/02/05 08:50
			EPO; JPO;	
			DERWENT	
1_	47	((magnet\$7 adj align\$5) and ring) and	USPAT;	2002/02/05 08:51
	•	semiconductor	EPO; JPO;	2002, 02, 00 00.01
		- Semiconductor	DERWENT	
_	1 1 3066	 optically adj align\$5	USPAT;	2002/02/05 08:56
	3000	optically adj aligned	EPO; JPO;	2002/02/03 08.30
	C10	(DERWENT	2002/02/05 00 57
_	612	(optically adj align\$5) and semiconductor	USPAT;	2002/02/05 08:57
			EPO; JPO;	
	_		DERWENT	
-	8	(USPAT	2003/06/02 08:10
		or ("6309909") or ("6326697") or		
		("5858815") or ("5137836") or		
		("4781969")).PN.		
-	10260	wood.inv.	USPAT;	2002/07/03 08:13
			US-PGPUB;	
İ			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	539	wood.inv. and alan	USPAT;	2002/07/03 08:13
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	232	(wood.inv. and alan) and (micron adj	USPAT;	2002/07/03 08:14
	232	technology)	US-PGPUB;	2002/07/03 00:14
		technology/	EPO; JPO;	
			DERWENT;	
]		IBM TDB	
_	1	("6268650").PN.	USPAT	2002/12/20 10:24
	425		USPAT	2002/12/20 10:24 2002/07/08 08:43
-	1	1 '		
_	331		USPAT	2002/07/08 08:57
-	140		USPAT	2002/07/08 08:57
_	90		USPAT	2002/07/08 08:57
_	425		USPAT	2002/07/08 08:43
-	331		USPAT	2002/07/08 08:57
-	140	1 '	USPAT	2002/07/08 08:57
_	90	', · · · · · · · · · · · · · · · · · ·	USPAT	2002/07/08 14:32
-	13		USPAT	2002/07/08 10:35
1		or ("6326700") or ("6268650") or		
	ļ	("5858815") or ("5817535") or ("5770032")		
		or ("4781969") or ("5073840") or		
	ļ	("5696033") or ("5834839") or		
		("6160714")).PN.		
-	8	(("6309909") or ("5858815") or ("5137836")	USPAT	2002/07/09 09:56
		or ("6077757") or ("6326697") or		
		("6165885") or ("5834320") or		
		("4781969")).PN.		
_	0		USPAT;	2002/12/19 15:00
		(dielectric adj (layer or film))) same	US-PGPUB;	1002, 12, 13 10.00
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
]	costys same (caths of archs of sebaraths)	DERWENT;	
			IBM TDB	
1	l	l	Tabra TAB	

-	0	(wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3 same (cut\$4 or dic\$3 or separat\$3)	EPO; JPO;	
			DERWENT;	
		5 ,, ,, ,,	IBM_TDB	0000/10/10 14 07
-	19	wafer adj (bond\$3 or attach\$3) near4	USPAT;	2002/12/19 14:07
		(dielectric adj (layer or film))	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
!			IBM_TDB	2002/12/10 14 20
-	0	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2002/12/19 14:38
		(dielectric adj (layer or film))) same	US-PGPUB;	
		test\$3	EPO; JPO; DERWENT;	
			IBM TDB	
	963	438/15,110,113,114.ccls.	USPAT	2002/12/19 14:38
_	1212	438/15,110,113,114.ccls.	USPAT;	2002/12/19 14:38
_	1212	430/13,110,113,114.0015.	US-PGPUB;	2002/12/19 14.50
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
		 438/15,110,113,114.ccls. and ((wafer adj	USPAT;	2002/12/19 14:40
		(bond\$3 or attach\$3) near4 (dielectric adj	US-PGPUB;	2002/12/13 14:40
		(layer or film))) same test\$3)	EPO; JPO;	
	}	(tayer or ritm)// same (escas)	DERWENT;	
			IBM TDB	
_	9	(wafer adj (dielectric adj (layer or	USPAT;	2002/12/20 08:18
1		film))) same test\$3	US-PGPUB;	2002/12/20 00.10
		IIIm/// Same Cescys	EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	13	(("5834839") or ("6389689") or ("6160714")	USPAT	2002/12/19 15:19
		or ("5977629") or ("6326700") or	OSTAT	2002/12/19 13:19
		("6268650") or ("5858815") or ("5817535")		
		or ("5770032") or ("5796170") or		
		("4781969") or ("5073840") or		
		("5696033")).PN.		
_	85		USPAT;	2002/12/20 08:42
		(cut\$3 or dic\$3 or slic\$3)	US-PGPUB;	
		(EPO; JPO;	
			DERWENT;	
			IBM TDB	
_	78	(wafer same dielectric same test\$3 same	USPĀT;	2002/12/20 09:38
		(cut\$3 or dic\$3 or slic\$3)) and	US-PGPUB;	
		semiconductor	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	348	1	USPAT;	2002/12/20 09:35
		film))) same test\$3	US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	322	1 ' '	USPAT;	2002/12/20 09:38
		film))) same test\$3) and semiconductor	US-PGPUB;	
1			EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000/10/22 55
-	98	, , , ,	USPAT;	2002/12/20 09:39
	1	film))) same test\$3) and semiconductor)	US-PGPUB;	
		and (cut\$3 or dic\$3)	EPO; JPO;	
			DERWENT;	
		/U.6.4.2.4.0.2.2.U.\ DNI	IBM_TDB	2002/12/20 12 24
-	1	1 '	USPAT	2002/12/20 10:24
_	3	(("5897337") or ("5858815") or	USPAT	2002/12/23 11:53
		("6389689")).PN.	HGDVW	2002/12/22 11-52
_	0197	1 , ,	USPAT	2002/12/23 11:53
_	9187	((balls adj grid adj arrays) or (BGA)) and semiconductor	USPAT; US-PGPUB;	2003/05/20 07:59
		Semiconductor	EPO; JPO;	
	1		DERWENT;	
			IBM TDB	
I	1	l	TDIJ_IDB	<u></u>

	1 1 1 1 1 1 1			1 0000 /05 /00 00 00
_	4418		USPAT;	2003/05/20 08:02
		and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	
		separat\$5)	EPO; JPO;	
			DERWENT;	
	1176	///balls add and add annoval on (DCA))	IBM_TDB USPAT;	2003/05/20 08:04
_	4476	' ' ' ' ' ' ' ' ' ' ' ' '	US-PGPUB;	2003/03/20 08:04
		and semiconductor) and (dic\$4 or cut\$4 or	EPO; JPO;	
	•	separat\$5 or saw\$4)		
			DERWENT; IBM TDB	
	955	///balla add arid add arraya) or (PCA))	USPAT;	2003/05/20 08:04
_	955		-	2003/03/20 08:04
		and semiconductor) and (dic\$4 or cut\$4 or	US-PGPUB;	
		separat\$5)) and (metal adj (film or	EPO; JPO;	
		layer))	DERWENT; IBM TDB	
	970	///balla add arid add arrays) or (BCA))	USPAT;	2003/05/20 08:04
-	970	((((balls adj grid adj arrays) or (BGA)) and semiconductor) and (dic\$4 or cut\$4 or	· ·	2003/03/20 08:04
			US-PGPUB;	
		separat\$5 or saw\$4)) and (metal adj (film	EPO; JPO;	
		or layer))	DERWENT;	
	1	(#20010052642#\\ DN	IBM_TDB	2002/05/20 00 10
-	i	("20010052642").PN.	US-PGPUB	2003/05/20 08:12
_	472		USPAT;	2003/05/20 08:52
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
	-	adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)	DERWENT;	
		1, -6-, 1, 1, 2, 3, 4613	IBM_TDB	0004/01/10 01 11
-	233		USPAT;	2004/01/12 08:09
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or (BGA)) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
		@ad<=20000616	IBM_TDB	
-	212		USPAT;	2003/05/21 08:23
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)		
-	206	1 ' '	USPAT;	2003/05/20 09:06
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6)		
-	1	(((wafer adj semiconductor) same (metal	USPAT;	2003/05/20 10:06
		adj (film or layer)) same (attach\$5 or	US-PGPUB;	
		bond\$4) same ((balls adj grid adj arrays)	EPO; JPO;	
		or (BGA)) same (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) same (dic\$5 or cut\$6 or	IBM_TDB	
		saw\$5)) and @ad<=20000616		
-	212		USPAT;	2003/05/21 09:00
-		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
	:	separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)		
-	172	, , , , , , , , , , , , , , , , , , ,	USPAT;	2003/05/21 09:24
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)) and dic\$5		
-	92	(((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:35
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
	1	grid adj arrays) or (BGA)) and	EPO; JPO;	
	1	semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM_TDB	
		or cut\$6 or saw\$5)) and (dicing or diced)		

-	70	((((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:36
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
-		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5)) and (dicing or		
		diced)) and (individual\$3 or each)		
-	70	((((wafer and (metal adj (film or layer))	USPAT;	2003/05/21 09:36
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5)) and (dicing or		
		diced)) and (individual\$3)		
_	6		USPAT;	2003/05/21 09:37
		and (attach\$5 or bond\$4) and ((balls adj	US-PGPUB;	
		grid adj arrays) or (BGA)) and	EPO; JPO;	
-		semiconductor and (dic\$4 or cut\$4 or	DERWENT;	
		separat\$5)) and @ad<=20000616) and (dic\$5	IBM TDB	
		or cut\$6 or saw\$5)) and (dicing or	1511_155	
		diced)) and (individual\$3 adj device)		
		(("6344401") or ("6566745")).PN.	USPAT	2004/01/12 07:56
_	241		USPAT;	2004/01/12 07:36
_	241	(wafer and (metal adj (film or layer)) and	·	2004/01/12 08:10
		(attach\$5 or bond\$4) and ((balls adj grid	US-PGPUB;	
		adj arrays) or ("BGA")) and semiconductor	EPO; JPO;	
		and (dic\$4 or cut\$4 or separat\$5)) and	DERWENT;	
	_	@ad<=20000616	IBM_TDB	0000/10/00 10 15
_	1	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2003/10/23 10:36
		<pre>same (attach\$5 or bond\$4) same ((balls adj</pre>	US-PGPUB;	
		grid adj arrays) or ("BGA")) same	EPO; JPO;	
		semiconductor same (dic\$4 or cut\$4 or	DERWENT;	ĺ
		separat\$5))) and @ad<=20000616	IBM_TDB	
-	2	(("6153448") or ("20020011859")).PN.	USPAT;	2003/10/24 12:35
			US-PGPUB	
-	4	(("6153448") or ("20020011859") or	USPAT;	2003/10/24 14:07
		("6064217") or ("5475317")).PN.	US-PGPUB	